

IN THE CLAIMS:

Please cancel claims 14-18, 23-26, 56-61, and 65-66, add new claim 69, and amend claims 19, 20, and 62 as follows:

1-18. (Canceled)

19. (Currently amended) ~~The method of claim 18,~~ A method for processing substrates comprising:

providing a first relative motion between at least one substrate and a polishing material by moving a polishing head in a planar motion, wherein the providing the first relative motion further comprises [[:]] moving the polishing material in a linear direction; and

providing a second relative motion between at least another substrate and the polishing material, wherein the first relative motion or the second relative motion further comprises rotating a platen supporting the polishing material.

20. (Currently amended) ~~The method of claim 18,~~ A method for processing substrates comprising:

providing a first relative motion between at least one substrate and a polishing material by moving a polishing head in a planar motion, wherein the providing the first relative motion further comprises [[:]] processing additional substrates utilizing the first relative motion between the at least one substrates and the polishing material before providing the second relative motion between the at least another substrate and the polishing material; and

providing a second relative motion between at least another substrate and the polishing material, wherein the first relative motion or the second relative motion further comprises rotating a platen supporting the polishing material.

21. (Previously presented) The method of claim 20, wherein the providing the second relative motion further comprises:

processing additional substrates utilizing the second relative motion between the at least another substrate and the polishing material.

22. (Previously presented) The method of claim 20 further comprising:

processing another batch of substrates utilizing the first relative motion between the substrates and the polishing material.

23-42. (Canceled)

43. (Previously presented) A method for processing substrates comprising:

providing a first relative motion between at least one substrate and a polishing material by moving the polishing material in a linear direction; and

providing a second relative motion between at least another substrate and the polishing material, wherein the first relative motion or the second relative motion further comprises rotating a platen supporting the polishing material.

44. (Previously presented) The method of claim 43, wherein the providing the first relative motion further comprises:

performing a chemical mechanical planarization process.

45. (Previously presented) The method of claim 43, wherein the providing the first relative motion further comprises:

rotating a platen supporting the polishing material.

46. (Previously presented) The method of claim 43, wherein the providing the second relative motion further comprises:

rotating a platen supporting the polishing material in a direction opposite a rotational direction of the first relative motion.

47. (Previously presented) The method of claim 43, wherein the providing the first relative motion further comprises:

moving a polishing head retaining the first substrate.

48. (Previously presented) The method of claim 43, wherein the providing the first relative motion further comprises:

moving the polishing head in a planar motion.

49. (Previously presented) The method of claim 43, wherein the providing the first relative motion further comprises:

processing additional substrates utilizing the first relative motion between the at least one substrates and the polishing material before providing the second relative motion between the at least another substrate and the polishing material.

50. (Previously presented) The method of claim 49, wherein the providing the second relative motion further comprises:

processing additional substrates utilizing the second relative motion between the at least another substrate and the polishing material.

51. (Previously presented) The method of claim 49 further comprising:

processing another batch of substrates utilizing the first relative motion between the substrates and the polishing material.

52. (Previously presented) The method of claim 43, wherein the first relative motion is opposite the second relative motion.

53. (Previously presented) The method of claim 43 further comprising:

processing a third substrate utilizing the first relative motion.

54. (Previously presented) A method for processing substrates comprising:
providing a first relative motion between at least one substrate and a polishing material by moving the polishing material in a linear direction;
providing a second relative motion between at least another substrate and the polishing material; and
flowing a temperature control fluid through passages disposed in a platen having the polishing material disposed thereon.

55. (Previously presented) The method of claim 54, wherein the flowing the temperature control fluid through the platen further comprises:
reducing the temperature of the polishing material.

56-61. (Canceled)

62. (Currently Amended) ~~The method of claim 56, wherein the~~ A method for processing substrates comprising:
providing a first relative motion between at least one substrate and a polishing material, wherein the providing the first relative motion ~~further~~ comprises ~~[[:]]~~ moving the polishing material in a linear direction;
providing a second relative motion between at least another substrate and the polishing material;
processing additional substrates utilizing the first relative motion between the at least one substrates and the polishing material before providing the second relative motion between the at least another substrate and the polishing material, wherein the first relative motion or the second relative motion comprises rotating a platen supporting the polishing material.

63. (Previously presented) The method of claim 62, wherein the providing the second relative motion further comprises:

processing additional substrates utilizing the second relative motion between the at least another substrate and the polishing material.

64. (Previously presented) The method of claim 62 further comprising:
processing another batch of substrates utilizing the first relative motion between the substrates and the polishing material.

65-66. (Canceled)

67. (Previously presented) A method for processing substrates comprising:
providing a first relative motion between at least one substrate and a polishing material;
providing a second relative motion between at least another substrate and the polishing material;

processing additional substrates utilizing the first relative motion between the at least one substrates and the polishing material before providing the second relative motion between the at least another substrate and the polishing material;
and

flowing a temperature control fluid through passages disposed in a platen having the polishing material disposed thereon.

68. (Previously presented) The method of claim 67, wherein the flowing the temperature control fluid through the platen further comprises:
reducing the temperature of the polishing material.

69. (New) The method of claim 43, wherein the first relative motion is provided by the integration of two perpendicular, linear drives to move the polishing material in a linear direction.